


IFW

TRANSMITTAL OF FORMAL DRAWINGS				Docket No. FIS9199980039US3	
In Re Application Of: COICO, ET AL.					
Application No. 10/752,255	Filing Date 1/6/04	Examiner TRAN, THANH Y.	Customer No. 32074	Group Art Unit 2822	Confirmation No. 4027
Invention: STRESS RESISTANT LAND GRID ARRAY (LGA) MODULE AND METHOD OF FORMING THE SAME					
Address to: Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450					
Transmitted herewith are:  3 sheets of formal drawing(s) for this application.					
<input checked="" type="checkbox"/> Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c).					
<div> Signature IRA D. BLECKER, REG. NO. 29,894 IBM CORPORATION 2070 ROUTE 52 HOPEWELL JUNCTION, NY 12533</div>			Dated: May 2, 2005		
<div>I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on  (Date)  Signature of Person Mailing Correspondence <b>HAND CARRY</b> Typed or Printed Name of Person Mailing Correspondence</div>					